

SUPPORTING INFORMATION

Table S1: Average photovoltaic performance of $\text{MA}_{0.6}\text{FA}_{0.4}\text{PbI}_3$ perovskite devices having different doping concentration of F4TCNQ dopant in FDT HTL in FB-SC direction at a scan rate of 0.05 V/s

F4TCNQ Dopant Concentration (wt%)	Open Circuit Voltage, V_{OC} (mV)	Short Circuit Current Density, J_{SC} (mA/cm^2)	Fill Factor, FF (%)	Efficiency (%)	Series Resistance, R_S ($\Omega \cdot \text{cm}^2$)	Shunt Resistance R_{Sh} ($\Omega \cdot \text{cm}^2$)
0	744.69	19.26	48.66	6.98	12.69	267
0.5	863.88	20.41	69.99	12.34	5.90	1215
1	935.64	20.54	70.87	13.63	4.62	1220
1.5	916.30	20.27	69.86	12.97	5.27	1381
2	902.85	19.90	65.05	11.69	7.34	1382

Table S2: J-V parameters (V_{OC} , J_{SC} , FF and PCE values) of ten (10) L-FDT devices in FB-SC direction from a single, random batch at a scan rate of 0.05 V/s

Sample No.	Open Circuit Voltage, V_{OC} (mV)	Short Circuit Current Density, J_{SC} (mA/cm^2)	Fill Factor, FF (%)	Efficiency (%)	Series Resistance, R_S ($\Omega \cdot \text{cm}^2$)	Shunt Resistance R_{Sh} ($\Omega \cdot \text{cm}^2$)
1	905.53	21.22	60.76	11.68	9.50	1085
2	930.89	20.03	62.13	11.58	9.36	1169
3	926.09	21.46	61.02	12.13	9.86	1134
4	942.09	20.06	60.88	11.50	10.22	1035
5	925.59	21.46	61.44	12.20	9.05	1017
6	899.92	20.72	63.77	11.89	7.79	1089
7	912.58	21.58	61.37	12.08	8.73	1130
8	915.38	21.21	61.34	11.91	9.00	1152
9	940.42	20.02	60.82	11.45	10.40	1070
10	905.25	20.95	63.44	12.03	7.83	1265

Table S3: J-V parameters (V_{OC} , J_{SC} , FF and PCE values) of ten (10) F-FDT devices in FB-SC direction from a single, random batch at a scan rate of 0.05 V/s

Sample No.	Open Circuit Voltage, V_{OC} (mV)	Short Circuit Current Density, J_{SC} (mA/cm^2)	Fill Factor, FF (%)	Efficiency (%)	Series Resistance, R_S ($\Omega \cdot \text{cm}^2$)	Shunt Resistance R_{Sh} ($\Omega \cdot \text{cm}^2$)
1	944.06	20.41	70.87	13.66	4.68	1251
2	951.63	21.03	71.47	14.30	4.17	1292
3	935.38	20.65	71.45	13.80	4.32	1134
4	920.08	20.50	68.94	13.01	5.18	1247
5	944.37	20.80	71.64	14.07	4.36	1278
6	933.99	20.38	69.67	13.26	5.18	1409
7	920.74	20.33	69.87	13.08	5.18	1440
8	923.81	20.11	71.79	13.34	4.38	941
9	935.38	20.65	71.45	13.80	4.32	1134
10	946.94	20.57	71.53	13.93	4.47	1080

Table S4: Stabilized current density and PCE of L-FDT and F-FDT PSCs at maximum power point (MPP)

Device	Voltage at MPP (V)	Stabilized PCE (%)	Stabilized Current Density (mA/cm ²)
L-FDT	~0.70	~11.87	~18.35
F-FDT	~0.79	~13.33	~18.68

Table S5: Hysteresis index (HI) of L-FDT and F-FDT PSCs calculated from J-V measurements in both FB-SC and SC-FB directions at a scan rate of 0.05 V/s

Device	Current Density at (V _{oc} /2) in FB-SC scan (mA/cm ²)	Current Density at (V _{oc} /2) in SC-FB scan (mA/cm ²)	Hysteresis Index (HI)
L-FDT	20.40	18.33	0.10
F-FDT	20.96	19.49	0.07

Table S6: Day wise PCE, J_{SC}, V_{OC} and FF values of a L-FDT PSC stored in a N₂ filled glovebox for 21 days (Scan direction: FB-SC, scan rate: 0.05 V/s)

Number of Days	Open Circuit Voltage, V _{oc} (mV)	Short Circuit Current Density, J _{SC} (mA/cm ²)	Fill Factor, FF (%)	Efficiency (%)
0	940.42	20.02	60.82	11.45
1	903.40	20.08	60.29	10.94
3	917.85	19.76	59.12	10.72
5	905.87	19.70	58.47	10.44
7	891.92	20.07	54.71	9.80
9	894.88	19.57	54.13	9.48
11	882.43	19.31	53.25	9.07
13	872.93	19.20	51.70	8.66
15	839.99	18.23	50.83	7.78
17	824.97	18.19	45.44	6.82
19	785.65	17.97	44.25	6.26
21	742.27	17.88	43.77	5.81

Table S7: Day wise PCE, J_{SC} , V_{OC} and FF values of a F-FDT PSC stored in a N_2 filled glovebox for 21 days (Scan direction: FB-SC, scan rate: 0.05 V/s)

Number of Days	Open Circuit Voltage, V_{OC} (mV)	Short Circuit Current Density, J_{SC} (mA/cm^2)	Fill Factor, FF (%)	Efficiency (%)
0	951.63	21.03	71.47	14.30
1	957.89	20.73	71.69	14.24
3	944.36	20.80	71.64	14.07
5	946.94	20.56	71.53	13.93
7	948.49	20.48	71.22	13.84
9	944.06	20.41	70.87	13.66
11	925.83	20.55	71.40	13.58
13	925.81	20.48	71.15	13.49
15	910.89	20.47	70.89	13.22
17	904.94	20.55	70.66	13.14
19	893.88	20.23	70.85	12.81
21	887.07	20.54	69.88	12.73

Table S8: Values of contact angles of water droplets on L-FDT, F-FDT and pristine FDT HTL films on three different spots of respective surfaces in both left and right directions from Fig. 5(B)-5(D)

HTL Layer	Contact Angle (Spot 1) (Degree)		Contact Angle (Spot 2) (Degree)		Contact Angle (Spot 3) (Degree)		Average Contact Angle with Standard Deviation (Degree)
	Left	Right	Left	Right	Left	Right	
Pristine FDT	82.7	81.9	80.8	81.5	81.9	82.2	81.8±0.6
L-FDT	76.8	77.9	77.5	76.3	79.1	78.9	77.8±1.1
F-FDT	86.8	87.2	87.3	87.6	86.6	86.2	87±0.5

Table S9: Relative normalized peak intensity, peak width, microstrain and dislocation density of aged perovskite films underneath pristine FDT, L-FDT and F-FDT HTL films, calculated by the spectral fitting from XRD measurement data

Characteristic Peak	HTL Layer on perovskite	Relative Normalized Peak Intensity	Peak Width (FWHM) (Degree)	Microstrain ($\times 10^{-3}$)	Dislocation Density ($\times 10^{11} \text{ cm}^{-3}$)
(110)	Pristine FDT	0.95	0.12709	4.51	0.25
	L-FDT	0.69	0.16279	5.80	0.41
	F-FDT	1.00	0.12991	4.62	0.26
(202)	Pristine FDT	0.13	0.20427	4.12	0.63
	L-FDT	0.33	0.18491	3.74	0.52
	F-FDT	0.15	0.19722	3.98	0.59
(220)	Pristine FDT	0.44	0.14953	2.60	0.33
	L-FDT	0.34	0.17234	3.00	0.44
	F-FDT	0.47	0.13917	2.41	0.29
(310)	Pristine FDT	0.33	0.14601	2.25	0.31
	L-FDT	0.22	0.17902	2.76	0.47
	F-FDT	0.33	0.15206	2.34	0.34
(224)	Pristine FDT	0.15	0.17884	2.13	0.44
	L-FDT	0.09	0.19386	2.31	0.52
	F-FDT	0.17	0.13216	1.57	0.24
(314)	Pristine FDT	0.10	0.20154	2.24	0.56
	L-FDT	0.06	0.24550	2.73	0.83
	F-FDT	0.11	0.20631	2.29	0.58

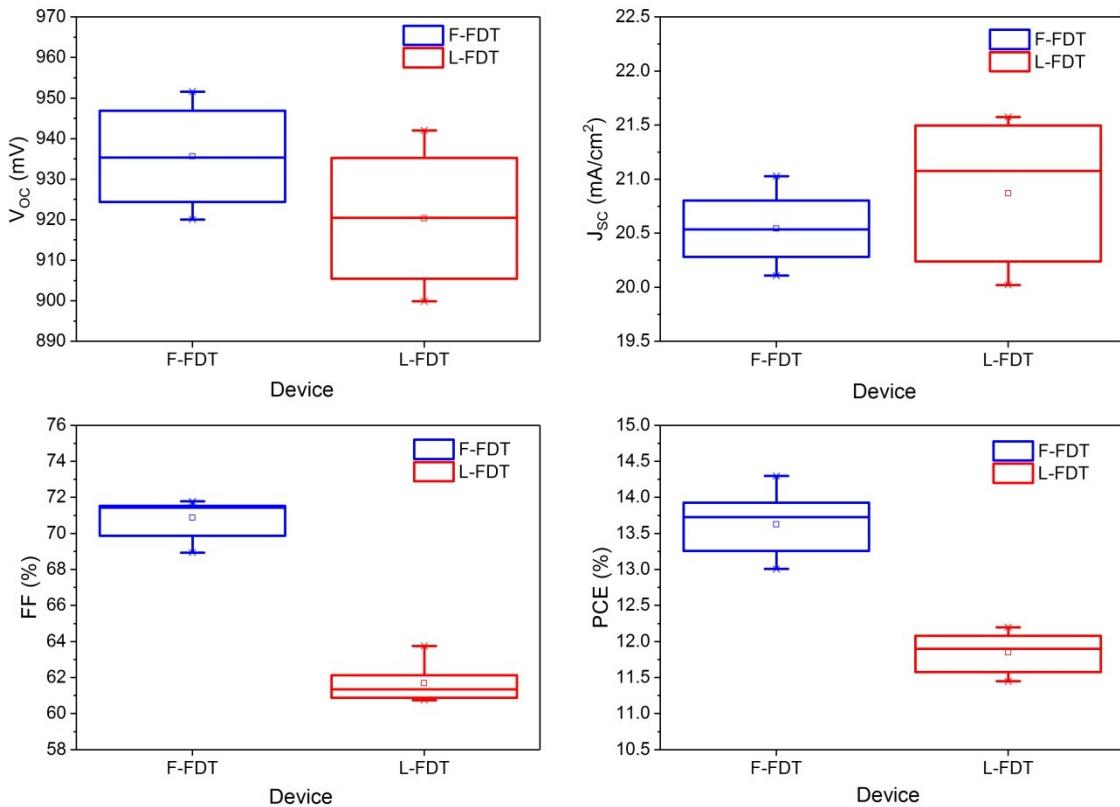


Fig. S1 Statistical box-chart showing the range of variation in (A) V_{OC} , (B) J_{SC} , (C) FF and (D) PCE in FB-SC direction obtained from ten identically fabricated L-FDT and F-FDT devices in a single, random batch at a scan rate of 0.05 V/s

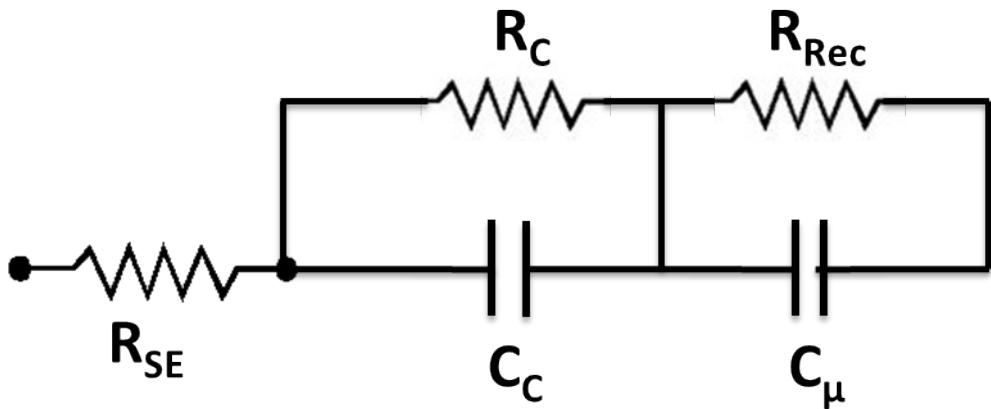


Fig. S2 Equivalent circuit model used to fit the experimental data from Nyquist plot at Fig. 2(B). The components R_S , R_C , C_C , R_{Rec} and C_μ denote the resistance originating from the wire connection and metal contact, contact resistance at perovskite/ETL or perovskite/HTL interface, bulk capacitance, recombination resistance and chemical capacitance respectively.